

## -60V P-Channel Enhancement Mode MOSFET

### Description

The AP30P06Y uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

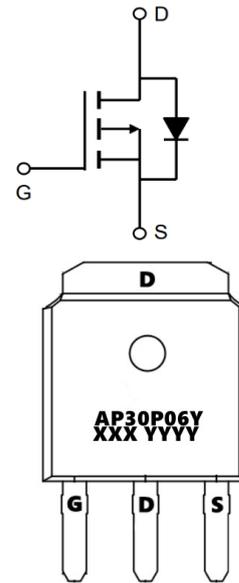
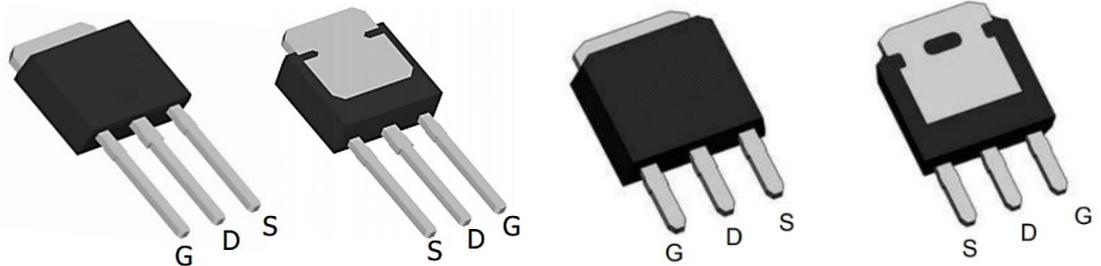
### General Features

$V_{DS} = -60V$   $I_D = -30A$

$R_{DS(ON)} < 25m\Omega$  @  $V_{GS} = -10V$  (Type: 20m $\Omega$ )

### Application

- Lithium battery protection
- Wireless impact
- Mobile phone fast charging



### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP30P06Y	TO-251L-3L	AP30P06Y XXXX YYYY	4000
AP30P06Y	TO-251S-3L	AP30P06Y XXXX YYYY	4000

### Absolute Maximum Ratings ( $T_C = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $-V_{GS} @ -10V^1$	-30	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $-V_{GS} @ -10V^1$	-27	A
IDM	Pulsed Drain Current <sup>2</sup>	-85	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	113	mJ
IAS	Avalanche Current	47.6	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation <sup>4</sup>	52.1	W
TSTG	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	62.5	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	2.4	$^\circ C/W$

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### Electrical Characteristics (T<sub>c</sub>=25°C unless otherwise noted)

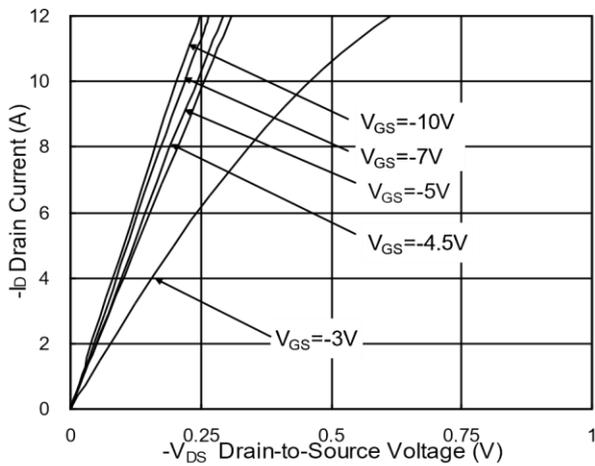
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-60	-68	---	V
ΔBVDSS/ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =-1mA	---	-0.035	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-10A	---	20	25	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-8A	---	26	33	
VGS(th)	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.0	-1.6	-2.5	V
ΔVGS(th)	VGS(th) Temperature Coefficient		---	4.28	---	mV/°C
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	5	
IGSS	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =-10V, I <sub>D</sub> =-18A	---	23	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	7	---	Ω
Q <sub>g</sub>	Total Gate Charge (-4.5V)	V <sub>DS</sub> =-20V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-12A	---	25	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	6.7	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	5.5	---	
Td(on)	Turn-On Delay Time	V <sub>DD</sub> =-15V, V <sub>GS</sub> =-10V, R <sub>G</sub> =3.3Ω, I <sub>D</sub> =-1A	---	38	---	ns
T <sub>r</sub>	Rise Time		---	23.6	---	
Td(off)	Turn-Off Delay Time		---	100	---	
T <sub>f</sub>	Fall Time		---	6.8	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, f=1MHz	---	3635	---	pF
C <sub>oss</sub>	Output Capacitance		---	224	---	
Crss	Reverse Transfer Capacitance		---	141	---	
I <sub>s</sub>	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	-35	A
ISM	Pulsed Source Current <sup>2,5</sup>		---	---	-70	A
VSD	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>s</sub> =-1A, T <sub>J</sub> =25°C	---	---	-1	V

#### Note :

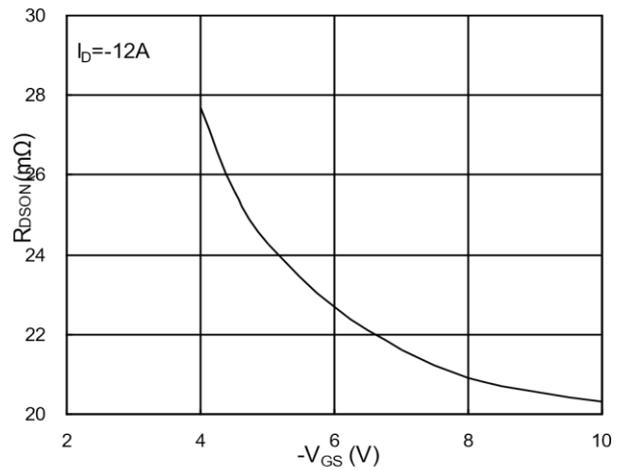
- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、 The EAS data shows Max. rating . The test condition is VDD=-48V,VGS =-10V,L=0.1mH,IAS =-47.6A
- 4、 The power dissipation is limited by 150°C junction temperature
- 5、 The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.

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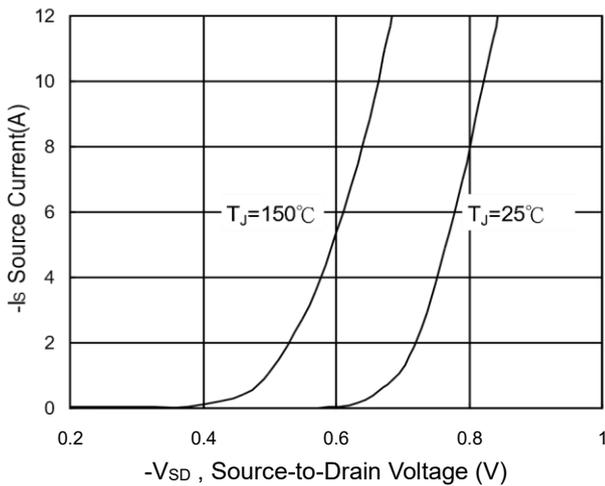
**Typical Characteristics**



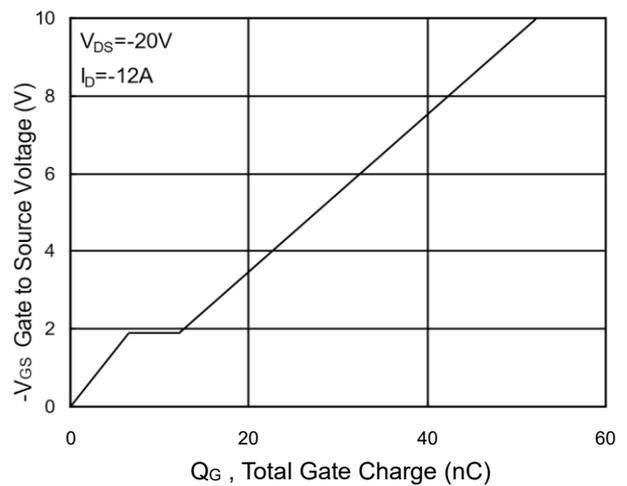
**Fig.1 Typical Output Characteristics**



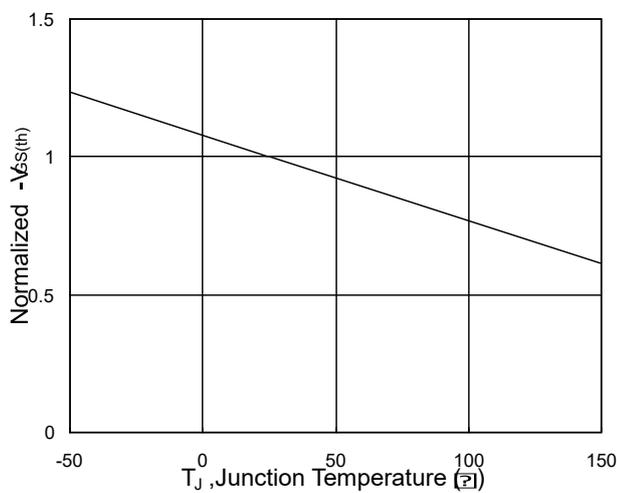
**Fig.2 On-Resistance v.s Gate-Source**



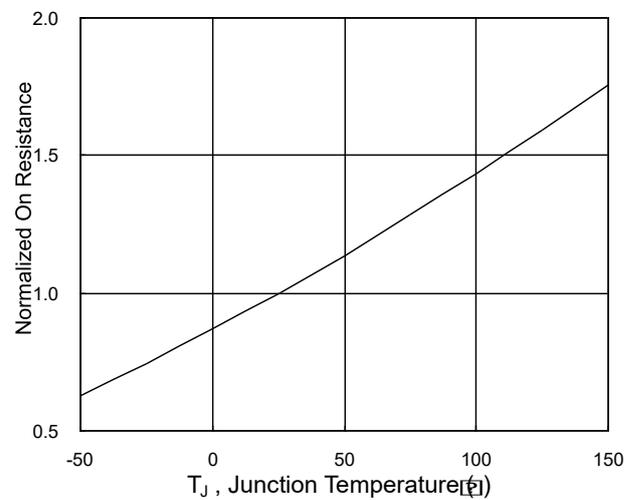
**Fig.3 Forward Characteristics Of Reverse**



**Fig.4 Gate-Charge Characteristics**

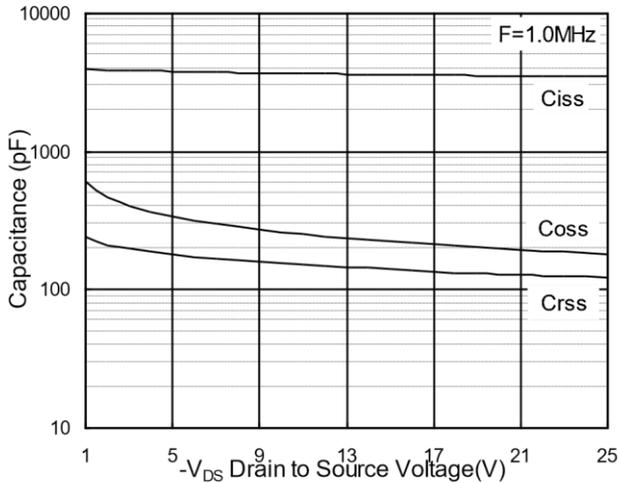


**Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$**

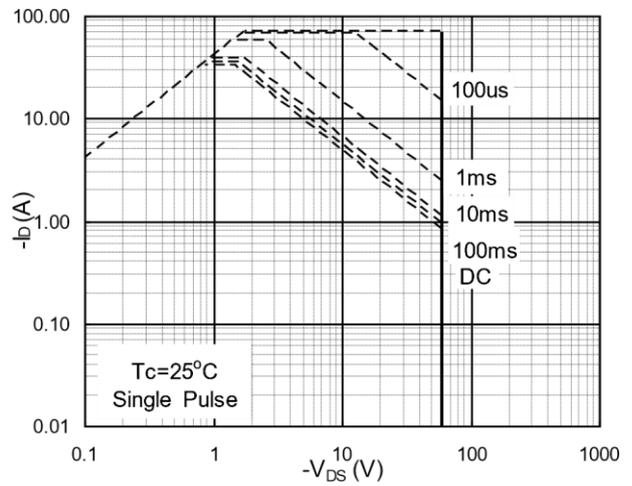


**Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$**

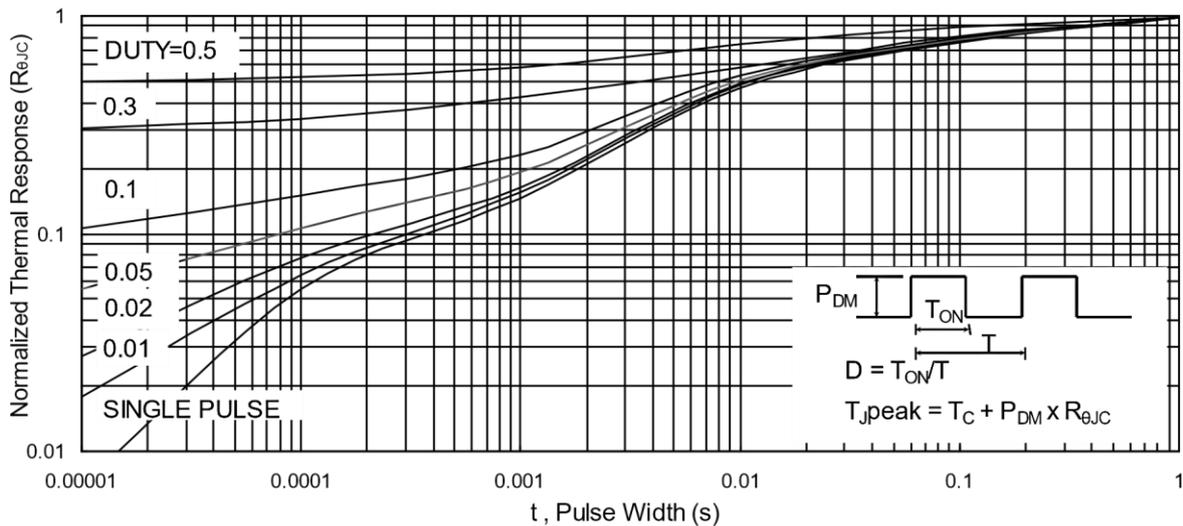
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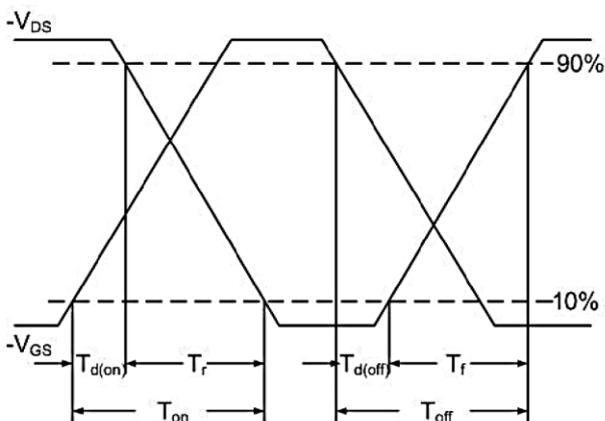
**Fig.7 Capacitance**



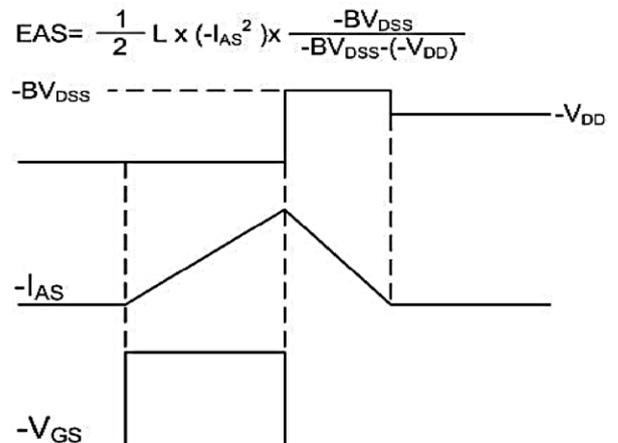
**Fig.8 Safe Operating Area**



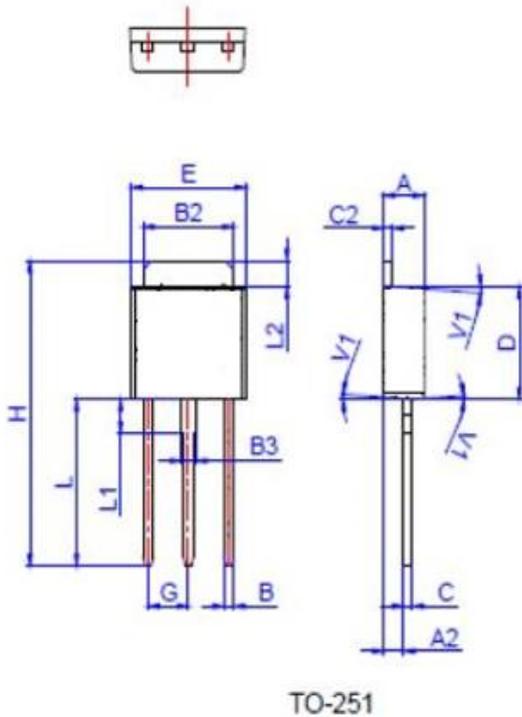
**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



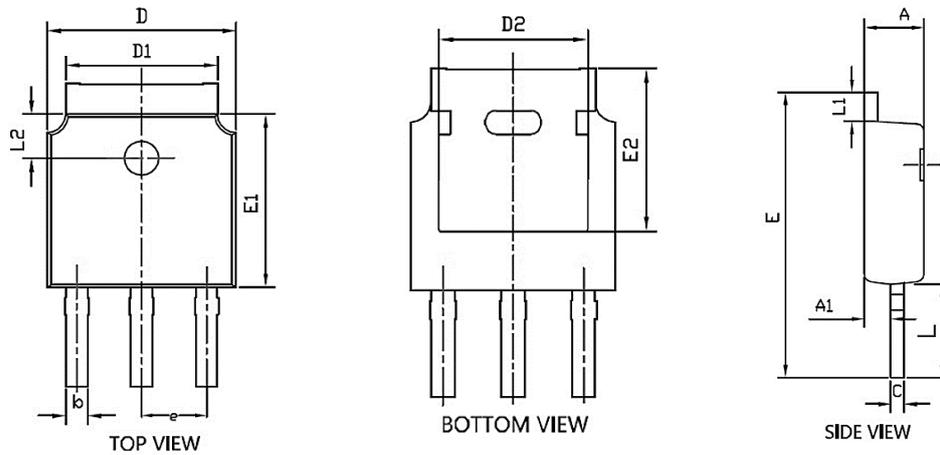
**Fig.11 Unclamped Inductive Waveform**

**Package Mechanical Data-TO-251L-3L**


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.20		2.40	0.086		0.095
A2	0.90		1.20	0.035		0.047
B	0.55		0.65	0.022		0.026
B2	5.10		5.40	0.200		0.213
B3	0.76		0.85	0.030		0.033
C	0.45		0.62	0.018		0.024
C2	0.48		0.62	0.019		0.024
D	6.00		6.20	0.236		0.244
E	6.40		6.70	0.252		0.264
G		2.30			0.091	
H	16.0		17.0	0.630		0.669
L	8.90		9.40	0.350		0.370
L1	1.80		1.90	0.071		0.075
L2	1.37		1.50	0.054		0.059
V1		4°			4°	

**Package Information -TO-251**

OUTLINE	TUBE (PCS)	INNER BOX (PCS)	PER CARTON (PCS)
TUBE	80	4,000	32,000

**Package Mechanical Data-TO-251S-3L**


Symbol	Common		
	mm		
	Mim	Nom	Max
A	2.2	2.3	2.4
A1	0.9	1.0	1.1
b	0.66	0.76	0.86
C	0.46	0.52	0.58
D	6.50	6.6	6.7
D1	5.15	5.3	5.45
D2	4.6	4.8	4.95
E	10.4	----	11.5
E1	6.0	6.1	6.2
E2	5.400REF		
e	2.286BSC		
L	3.5	4.0	4.3
L1	0.9	---	1.27
L2	1.4	---	1.9